

Title (en)
SYSTEMS, METHODS, AND MEDIA FOR MANUFACTURING PROCESSES

Title (de)
SYSTEME, VERFAHREN UND MEDIEN FÜR HERSTELLUNGSPROZESSE

Title (fr)
SYSTÈMES, PROCÉDÉS ET SUPPORTS POUR PROCÉDÉS DE FABRICATION

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EP 21767468 A 20210309

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Abstract (en)
[origin: WO2021183468A1] A manufacturing system is disclosed herein. The manufacturing system includes one or more stations, a monitoring platform, and a control module. Each station of the one or more stations is configured to perform at least one step in a multi-step manufacturing process for a component. The monitoring platform is configured to monitor progression of the component throughout the multi-step manufacturing process. The control module is configured to dynamically adjust processing parameters of each step of the multi-step manufacturing process to achieve a desired final quality metric for the component.

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Citation (search report)
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• [A] US 2007005525 A1 20070104 - COLLETTE L P III [US], et al
• [A] EP 0671677 B1 19990317 - MATSUSHITA ELECTRIC IND CO LTD [JP]
• [A] US 2019118300 A1 20190425 - PENNY RYAN WADE [US], et al
• See also references of WO 2021183468A1

Designated contracting state (EPC)
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